



## Materials Declaration Form


<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>24-09-2020</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
	<b>Legal Declaration *</b>
	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C64T-FCU6T/TF	JCPT*3T64ATA	A	996N	24-09-2020
	Amount	UoM	Unit type	ST ECOPACK Grade
	0.42	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260 DEGREES	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC125)	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
WL CSP	Not Applicable	4	No lead	
Comment	Package : A0Z7 WL CSP ULTRA-THIN 8508309			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product









Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	JCPT*3T64ATA				7000000.0	1000000.3
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.317	mg	supplier	die	Silicon (Si)	7440-21-3		0.298	mg	940063	707220
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	6309	4746
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	3155	2373
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	50473	37972
Polyimide	M-011 Other inorganic materials	0.011	mg	supplier	PI	Polyimide	497926-97-3		0.011	mg	1000000	25390
Sputter Layer	Metal	0.000	mg	supplier	Titanium(Ti)	Titanium(Ti)	7440-32-6		0.000	mg	1000000	336
RDL Layer	Metal	0.007	mg	supplier	Copper(Cu)	Copper(Cu)	7440-50-8		0.007	mg	1000000	16694
UBM	Metal	0.008	mg	supplier	Copper(Cu)	Copper(Cu)	7440-50-8		0.008	mg	1000000	19168
Solder Ball(98.25Sn / 1.2Ag / 0.5Cu/0	Copper Tin & its alloys	0.052	mg	supplier	Solder Ball	Solder Ball	7440-31-5		0.051	mg	987388	121079
				supplier	Solder Ball	Silver(Ag)	7440-22-4		0.001	mg	12060	1479
				supplier	Solder Ball	Copper(Cu)	7440-50-8		0.000	mg	502	62
				supplier	Solder Ball	Nickle(Ni)	7440-02-0		0.000	mg	50	6
Lamination tape(LC2824H)	M-011 Other inorganic materials	0.027	mg	supplier	Backside coating material	Polyethylene terephthalate	25038-59-9		0.009	mg	330000	20947
				supplier	Backside coating material	Silica	Un-defined		0.005	mg	170000	10791
				supplier	Backside coating material	Silicone	9016-00-6		0.001	mg	20000	1270
				supplier	Backside coating material	Acrylic resin	Un-defined		0.002	mg	80000	5078
				supplier	Backside coating material	Epoxy resin	Un-defined		0.001	mg	50000	3174
				supplier	Backside coating material	Carbon Black	1333-86-4		0.000	mg	10000	635
				supplier	Backside coating material	Polyethylene terephthalate	25038-59-9		0.009	mg	340000	21582







